
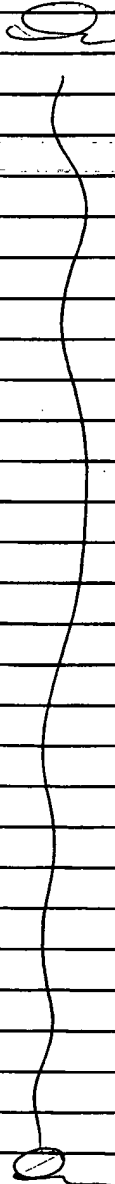

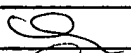

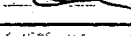

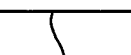
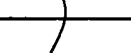


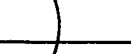

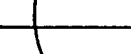

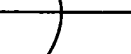
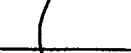

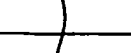




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				FILING DATE August 1, 2003		GROUP 2812	
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	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
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<i>a</i>	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
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	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control			
EXAMINER <i>[Signature]</i>				DATE CONSIDERED <i>8/10/04</i>			

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